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Docket No.: SENS.007US1



July 15, 2003

Mail Stop Patent Application

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Enclosed herewith for filing is a patent application, as follows:

Inventor: Wayne Glenn Renken

Title: System and Method for Heating and Cooling Wafer at Accelerated Rates

- X Check in the amount of \$624.00
- X Return Receipt Postcard
- X This Transmittal Letter (in duplicate)
- 12 pages Specification (not including claims)
- 5 pages Claims
- 1 page Abstract
- 5 Sheets of Formal Drawings

☐ Other:

☒ Applicant asserts entitlement to small entity status for the attached patent application

## CLAIMS AS FILED

For	Number		Number		Rate		Basic Fee
	<u>Filed</u>		<u>Extra</u>				
Total Claims	29	-20 =	9	x	\$9.00	=	\$ 81.00
Independent Claims	7	-3 =	4	x	\$42.00	=	\$ 168.00
<input type="checkbox"/>	Fee of _____ for the first filing of one or more multiple dependent claims per application						\$ 0.00
<input type="checkbox"/>	Fee for Assignment Recordation						\$ 0.00
<input checked="" type="checkbox"/>	Total fee for filing the patent application in the amount of						\$ <u>624.00</u>
<input checked="" type="checkbox"/>	The Commissioner is hereby authorized to charge any additional fees, which may be required, or credit any overpayment to Deposit Account 502664.						

EXPRESS MAIL LABEL NO:

EU962645425US

Respectfully submitted,

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